IN THE SPECIFICATION:

Please amend the specification as follows:

Please substitute the paragraph beginning at page 2, line 25, and ending on page 3, line 6, with the following.

-- In order to solve the ~~above mentioned~~ above-mentioned problems, a semiconductor exposure apparatus performs precise temperature control by an air conditioner so as to keep the temperature in the apparatus constant. The electrical components such as the driving circuit, sensor amplifier, and control board are accommodated in a box, or the like, so as not to leak heat generated in them. By flowing temperature adjusted air in the box, heat is not dissipated outside from the box. --

Please substitute the paragraph beginning at page 3, line 12, with the following.

-- As for the performance of an exposure apparatus, increases in accelerations as well as synchronization accuracy of a reticle stage and a wafer stage have been demanded to increase the throughput. To meet this demand, there has been proposed a mechanism, in which a counter mass, which moves in a direction opposite to the driving direction of a stage so as not to transmit vibrations generated upon stage driving outside the stage, is provided to receive a reaction force generated upon stage driving. Mounting of this mechanism also increases the size of an exposure apparatus. --

Please substitute the paragraph beginning at page 4, line 2, with the following.

-- The present invention has been made in consideration of the ~~above-mentioned~~ above-mentioned background, and has as its object to suppress an increase in size of a device manufacturing apparatus such as an exposure apparatus, and at the same time, to effectively prevent adverse effects caused by heat generation in a component. --

Please substitute the paragraph beginning at page 4, line 9, with the following.

-- According to the present invention, there is provided a device manufacturing apparatus for use in the manufacture of a device, the apparatus comprising a duct for ~~flowing~~ causing a temperature adjusting gas to flow, a first component arranged outside the duct to detect a state of a predetermined portion outside the duct, or to drive or to control the predetermined portion, and a second component arranged in the duct and electrically connected to the first component to receive an electrical signal that pertains to the state of the predetermined portion from the first component, or to supply an electrical signal generated to drive or to control the predetermined portion to the first component. According to the present invention, e.g., mounting the second component in the duct can suppress an increase in size of the device manufacturing apparatus and prevent adverse effects caused by heat generated in the second component. --

Please substitute the paragraph beginning at page 5, line 25, and ending on page 6, line 6, with the following.

-- The present invention can be ~~grasped as~~ a device manufacturing method using the ~~above-mentioned~~ above-mentioned device manufacturing apparatus. For example, if the ~~above~~

~~mentioned~~ above-mentioned device manufacturing apparatus is configured as an exposure apparatus, the exposure apparatus can be used in an exposure step in a lithography step, including a step of applying a photosensitive agent, the exposure step, a development step, an etching step, and the like. --

Please substitute the paragraph beginning at page 7, line 26, and ending on page 8, line 18, with the following.

-- The exposure apparatus comprises three booths, i.e., a main body booth A1, a transport booth A2, and an air conditioning booth A3. The main body booth A1 has a basic function of projecting and transferring the pattern of a reticle (master) onto a wafer (substrate) coated with a photosensitive agent. The transport booth A2 has a mechanism for loading the reticle and the wafer coated with the photosensitive agent to the main body booth A1 and unloading the wafer after exposure from the main body booth A1. The transport booth A2 typically has a transport robot, a unit which ~~pre-aligns~~ pre-aligns the reticle and wafer, and the like. The air conditioning booth A3 has a temperature adjusting device, which performs temperature control so as to continuously keep the temperature in the main body booth A1 and transport booth A2 at a constant temperature. Note that the exposure apparatus also comprises a control unit (not shown) for controlling the exposure apparatus, in addition to the ~~above-mentioned~~ above-mentioned components. --

Please substitute the paragraph beginning at page 15, line 4, with the following.

-- Assume that these conditions are satisfied and that the temperature of the temperature adjusting air is set to about 23°C. In this case, the temperature of the air at the inlet of the exhaust duct A13 becomes 25°C or less, and thus, heat generation in the second electrical components such as the circuit boards, the sensor amplifiers, and the like, in the exhaust duct A13 can sufficiently be suppressed. In addition, under these conditions, a change in temperature in the exhaust duct A13 is about 1°C. Hence, if a change in temperature of about 1°C is allowed, in, e.g., a measurement device in which a measurement error may be caused by a change in temperature of an electrical component such as a sensor amplifier, the electrical component of the measurement device can be arranged in the exhaust duct A13. --

Please substitute the paragraph beginning at page 17, line 12, with the following.

-- Fig. 6 is a view schematically showing an example of a shutter structure suitably adopted in the opening portion shown in Fig. 5. In this arrangement, two shutter plates (slide panels) D1 are provided. The two shutter plates D1 are slidably guided by a guide D3. Stretchable members D4 are attached to the opposing portions of the two shutter ~~plate~~ plates D1. The stretchable member D4 is preferably made of a material (e.g., a sponge), which has not only high stretchability, but also high heat insulating properties. A heat insulating member is preferably placed inside or outside the shutter ~~plate~~ plates D1. --

Please substitute the paragraph beginning at page 18, line 26, and ending on page 19, line 13, with the following.

-- In step 3 (wafer manufacture), a wafer is manufactured by using a material such as silicon. In step 4 (wafer process), called a preprocess, an actual circuit is formed on the wafer with the ~~above-mentioned~~ above-mentioned exposure apparatus by lithography using the prepared mask and wafer. Step 5 (assembly), called a post process, is the step of forming a semiconductor chip by using the wafer formed in step 4, and includes an assembly process (dicing and bonding) and a packaging process (chip encapsulation). In step 6 (inspection), the semiconductor device manufactured in step 5 undergoes inspections such as an operation confirmation test and a durability test. After these steps, the semiconductor device is completed and shipped in step 7. --

Please substitute the paragraph beginning at page 20, line 4, with the following.

-- According to the present invention, by arranging the second component in a duct, an increase in size of a device manufacturing apparatus can be suppressed, and adverse effects, which may be caused by heat generated in the second component, can be prevented. --